Making our world more productive



## Bulk specialty gas supply.

# Debottlenecking the electronics material supply chain from material production to fab consumption.

Dr. HokTsan Lam, Head of Business Development, Linde Electronics 17 October 2019

- The leading industrial gases and engineering company
- Formed in 2018 with the merger of Linde AG and Praxair, Inc – two world-class companies with nearly 140 years of shared history and successful achievements

# One Linde

Uniting with a shared Vision, Mission and Strategic Direction, and demonstrating our Values and Behaviors in everything we do

## 2 million+

#### customers

Establishing a more diverse and balanced portfolio

# 100+

#### countries

Enabling strong, complementary positions in all key geographies and end markets



## ~\$15 millions

charitable giving and sponsorships in 2018

Supporting our communities through contributions and employee volunteerism

# ~80,000

#### employees

Achieving our full potential, individually and collectively

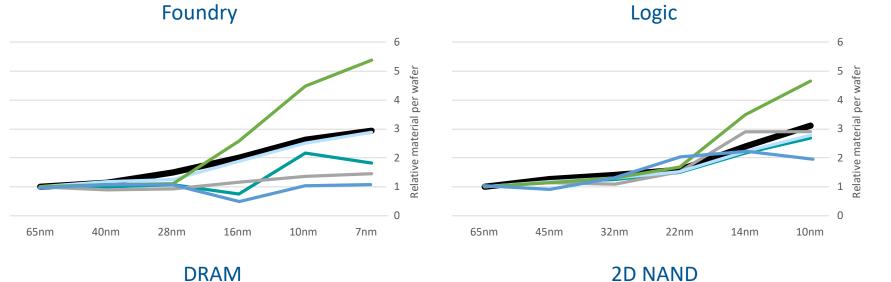
6,500+

active patent assets worldwide

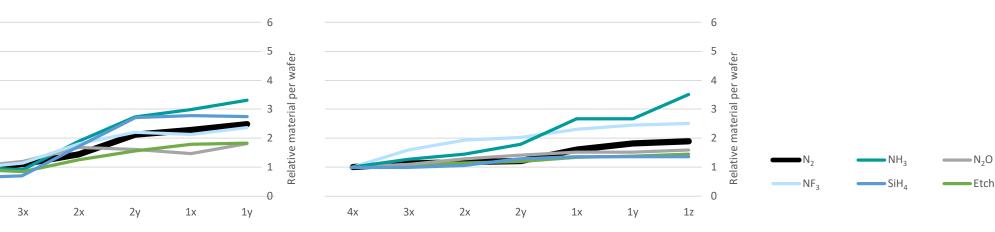
Leading with innovative products, solutions and technologies

## Material consumption increases with process complexity Nitrogen and Electronic Material : relative volume vs nodes









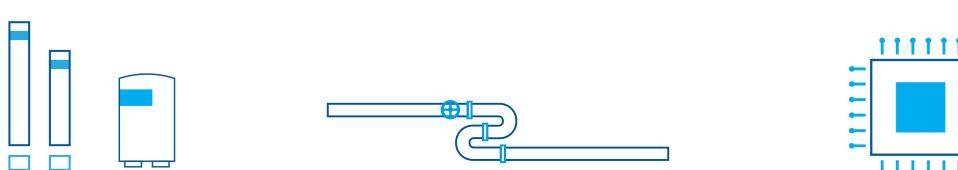
Source: IC Knowledge model

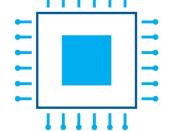
4x

6x

When bulk gas demand increases We build a larger nitrogen generator and pipeline







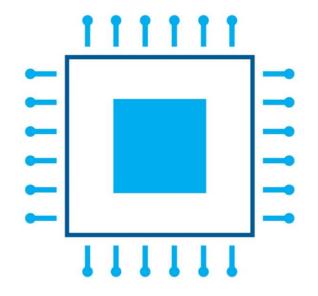
Nitrogen generator

Fab

When bulk gas demand increases We build a larger nitrogen generator and pipeline





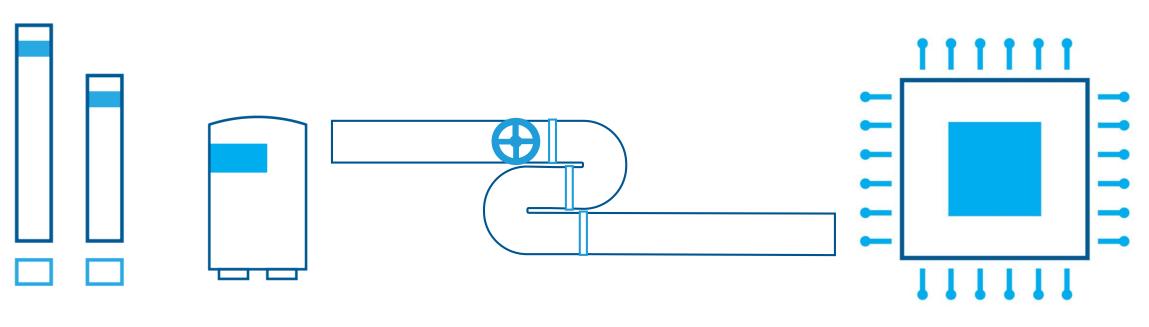


Nitrogen generator

Fab

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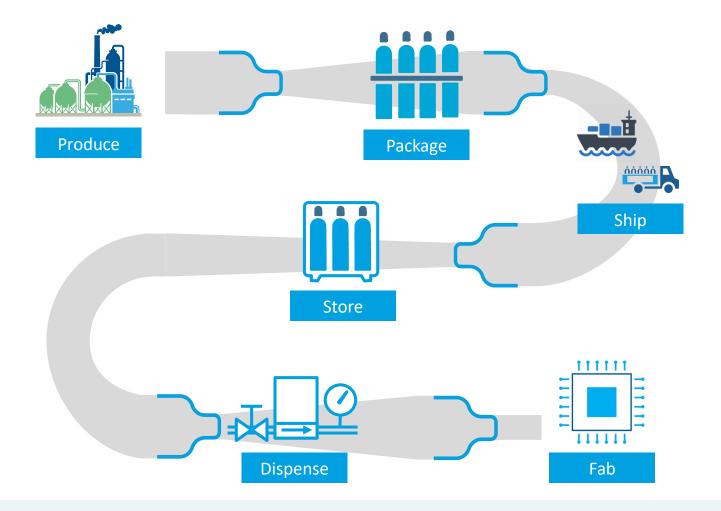
Nitrogen generator

Fab

### Electronic materials are not as simple

Need to debottleneck entire supply chain, sometimes over 1,000s of km

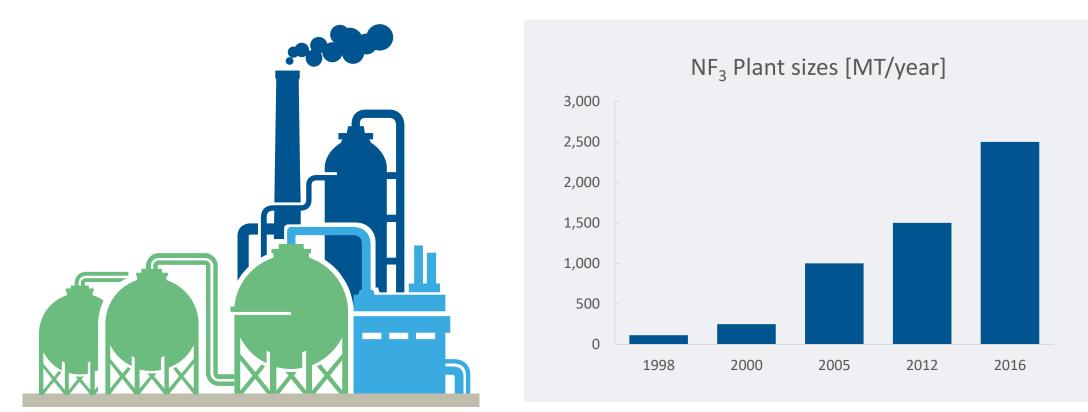




Whole supply chain is called Bulk Special Gas Supply Chain(BSGS)

## Electronic material production capacity scales with demand But can be located 1,000s of kilometers from the fab





No NF<sub>3</sub> production in Taiwan, ASEAN, or Europe



## Different packaging is required for different types of material



#### Ampoules

 Organometallic metal and silicon precursors
DOT4B, 8 or UN1A1, UN1H1

TDMAH TDMAT TDMAZ TSA



#### Low vapor pressure

• Service pressure up to 500psig DOT 4AA, 4BA, 4BW, 8AL, UN1A1, 3A

#### DCS TCS C<sub>2</sub>H<sub>2</sub> (stabilized) HCDS C<sub>x</sub>H<sub>y</sub> NH<sub>3</sub> Cl<sub>2</sub>

#### **High Pressure**

• Service pressure up to 2900psig DOT 3AA

NH <sub>3</sub>	Cl <sub>2</sub>
N <sub>2</sub> O	CF <sub>4</sub>
NF <sub>3</sub>	$C_2F_6$
SiH <sub>4</sub>	Kr
AsH <sub>3</sub>	CHF <sub>3</sub>
HBr	$C_4F_8$
WF <sub>6</sub>	СО
CO <sub>2</sub>	$C_3H_6$
PH <sub>3</sub>	Mixtures

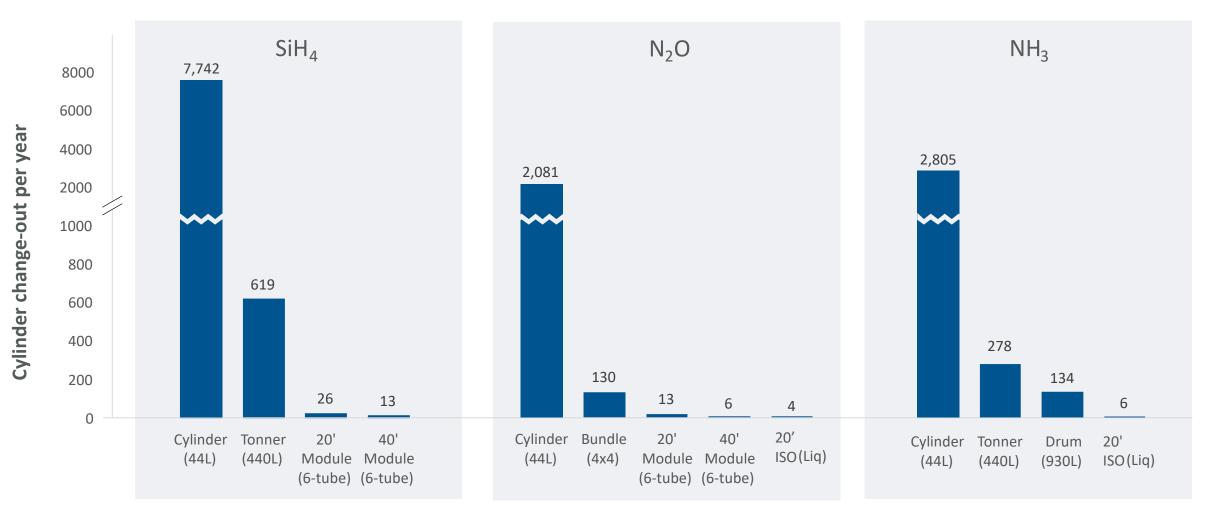




## Bulk package impact – changeout frequency Gen 8.5 TFT LCD Fab (~90k panels/month)



Package change frequency comparison



## Shipping Cost Impact Case study N<sub>2</sub>O: 20' Container from Korea to Taiwan



- Unit Shipping Cost Saving
- Round trip basis
- Each shipping vessel assumed maximum loading

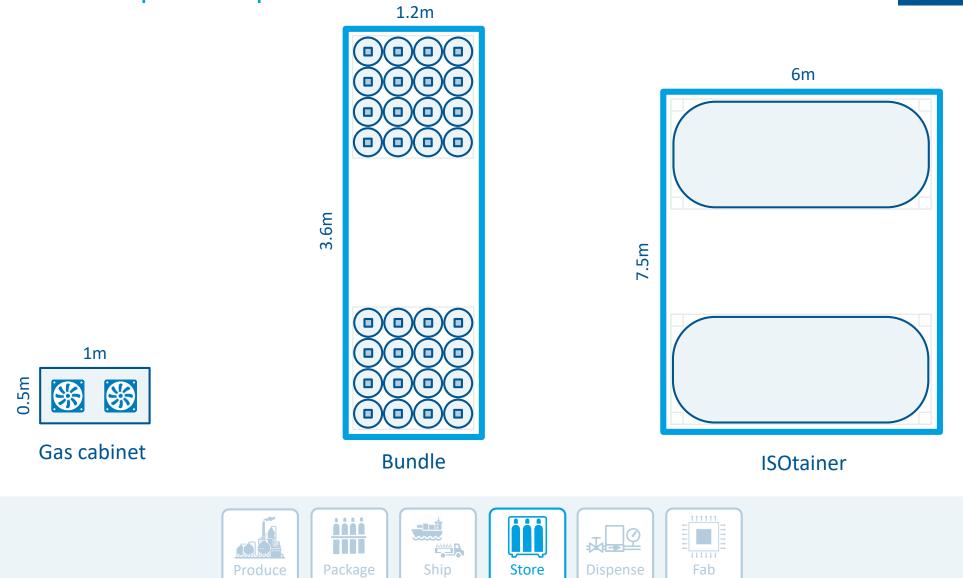




#### Relative shipping cost

## Package Footprint Area / mass samples – top view

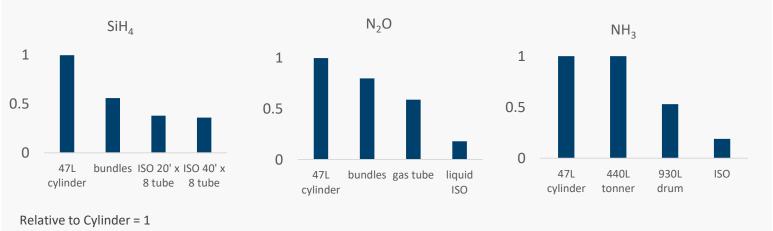




## Package Footprint Relative area / mass - efficient use of space



- Scaling up the size of package generally reduces the footprint of gas storage in a fab
- Comparison to a single gas cabinet footprint, an ISO container can achieve the following area/mass improvement
  0.2 N<sub>2</sub>O (20' liq ISO)
  0.36 NH<sub>3</sub> (20' ISO)
  0.2 SiH₄ (40' TT)
- Larger packages reduce total material footprint





### Larger panels, temperature controls, flow control benefits







Programmable Logic Controller (PLC) Provides fully automated control of the bulk system with maximum uptime.



#### **BSGS** Panel

Redundant plc, sensors and manifold

- increased automation
- failsafe operation
- lower maintenance = higher uptime



### Key benefits



#### SAFETY

- Majority of systems are located outdoors of facilities and are treated as unmanned systems
- Human cylinder change frequencies minimized
- Traffic of cylinder movement within the facility reduced

#### QUALITY

- Reduced material variability
- Reduced contamination risks
- Reduced package defect probability

#### PERFORMANCE

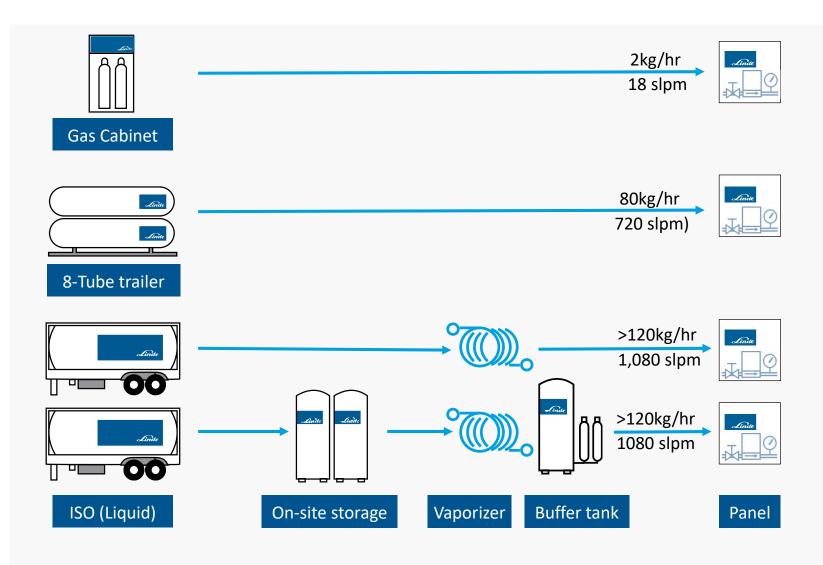
- Higher material availability
- Increased automation +data
- Better fab footprint utilization



## Case study : N<sub>2</sub>O Keeping pace with customer demand



- Customer demand increased, but area for material storage was limited
- Largest possible system, to-date, based on two 50MT on-site storage tanks
  - Max flow >120kg/hr
  - High purity liquid N<sub>2</sub>O vaporization
  - Consideration of space availability and number of cylinder changeout

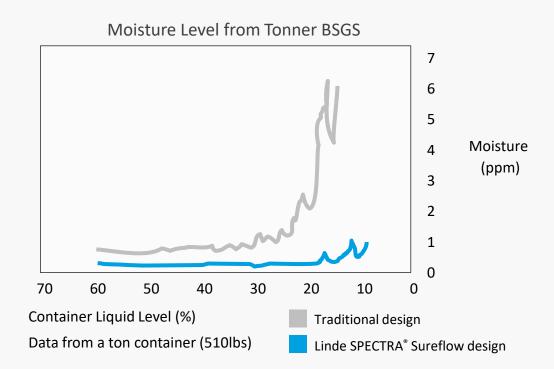


## Case study : NH<sub>3</sub>

# Linde

#### Reduced levels of delivered moisture

- Vapor withdrawal BSGS: characterized by a gradual increasing H<sub>2</sub>O concentration near cylinder end point.
- Heat transfer a strong function of heating blanket design.
- Linde Spectra Sureflow minimizes H<sub>2</sub>O carryover at the tonner end-of-life.



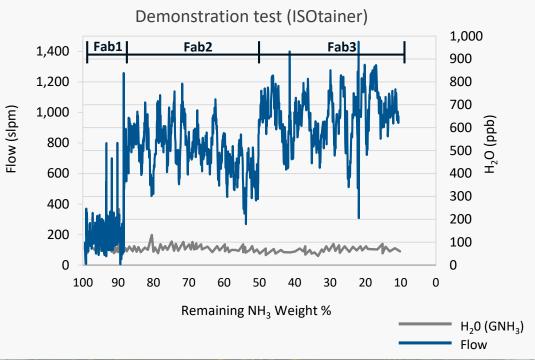


### Case study : NH<sub>3</sub>

#### Higher tolerance to variable flow

- Linde design maximized the heat transfer into liquid  $\rm NH_3$  at sustainable peak flow but minimizes  $\rm H_2O$  carryover
  - H<sub>2</sub>O unaffected by the surge of flowrates
  - H<sub>2</sub>O remained low even near EOL (end of life)







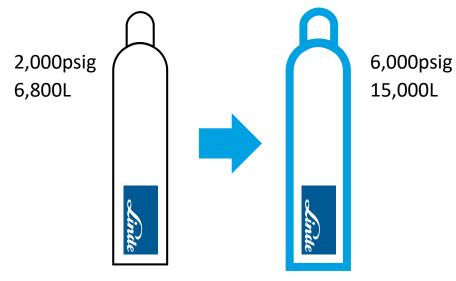
### Case study : High capacity packages

#### Challenges

- Increase the working pressure of cylinder and valve to sustain up to 6,000psig
- Maintain leak rate < 10<sup>-8</sup> mbar-L/s

#### **Potential Benefits**

- Higher fill capacity (potentially 2-3x)
- Improved cylinder utilization (up to 10% material saving)
- Plug-&-play drop-in replacement
- Improved footprint (area/mass)



190K wspm DRAM Fab	2,100psig Fill	6,000psig Fill	
Fill density (L/cyl)	6,800	15,000	
Usage rate (cyl/mon)	218	94	
Cylinder utilization	92%	97%	
			Savings
Cylinder changeout	2,600	1,100	1,500
Heel loss (L/yr)	1,400,000	500,000	900,000



Debottlenecking in the fab Wafers used to be carried by hand, but now travel in automated wafer tracks





Conclusion

Linde's approach to BSGS – It is not just a larger package or panel, but the ability to debottleneck the entire supply chain

111111 Fab 11111 Dispense Produce Package Ship Store Store Ship 111111 Package Dispense Fab Production



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## Acknowledgement

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